

承 认 书

Specification for approval

客户名称:

Customer: _____

产品名称:

Description: _____ TF 外焊

客户料号:

Customer part no: _____

亿创兴产品编号:

P/N: _____ KLJ07002

承认书编号:

Approval sheetno: _____

承认日期:

Approval date: _____

客户确认 CUSTOMER APPROVED	核 准 APPROVED	审 核 ENGINEER	经 办 CHECK

敬请盖印承认规格之后，将一份交回给本公司，谢谢!

Please return 1sets of this form to confirm your approval of the product specification,thank you!

深圳市亿创兴电子有限公司

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业务负责人: _____

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一. SCOPE(适用范围)

This specification is applied to the requirements for TFR Memory Card Connector. This specification covers the materials, ratings, electrical, mechanical and environmental performance of the applicable product description and test method.

本规范适用 TFR Memory Card 连接器，内容包括：物料规格，产品规格及电气特性，机构特性，环境特性及测试方式。

二. PRODUCT NAME AND PART NUMBER(产品名称和料号):

Product Name 产品名称	Part Number 产品料号
T-flash push type	KLJ07002

三. MATERIAL(材质)

3-1 Insulator:

绝缘体: High Temperature Plastic, UL94V-0

3-2 Contact:

端子: Phosphor Bronze

Plating(电镀): Gold Over Ni On Contact Area & Tin/Lead Over Ni

3-3 Cover:

铁壳: SUS

Plating(电镀): Gold plated on peg

四. GENERAL SPECIFICATION(基本规格):

Product shall be of the design, construction and physical dimensions Specified in the applicable product drawing.

产品要符合产品图规定的设计，结构和尺寸要求。

4-1 Rated Voltage(最大允许电压): 100V(MAX)。DC/AC

4-2 Rated Current(最大允许电流): 0.5A

4-3 Operating environment and temperature(使用环境及温度) -25℃~+85℃

4-4 Storage temperature Range(存储温度范围). -40℃~+85℃

4-5 Operating temperature Range(使用湿度范围).95%R.H.MAX

五. FIGURE AND DIMENSION(外形与尺寸):

放入产品外形及基本尺寸图

(见产品图面之规格)

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NO. 序号	ITEM 项目	CONDITION AND TEST METHOD 测试条件与方法	SPECIFICATION 规格	
六. ELECTRICAL (电气性能):				
6-1	CONTACT RESISTANCE 接触阻抗	1.The test method complies with EIA-364-06 测试方法依照 EIA-364-06	connector resistance 接触阻抗	100mΩ MAX
6-2	INSULATION RESISTANCE 绝缘阻抗	1.Test method complies with EIA-364-21. 测试方法依据 EIA-364-21 2.1000MΩ Min,Initial 100 MΩ Min after 1 minute@500VDC across adjacent PIN. 在相邻两端子通上 500V 直流电压, 起始阻抗在 100 MΩ 以上, 1 分钟后需在 1000MΩ 以上。	Insulation resistance 绝缘阻抗	1000MΩ MIN
6-3	DIELECTRIC STRENGTH 耐电压	1.The test method complies with EIA-364-20 测试方法依照 EIA-364-20 2.No shorting during 1 minute@500VAC rms with 1mA Max current leakage 施加 500V 交流电压及 1mA 最大漏电流时在 1 分钟内不短路	appearance 外观	No damage or deformation 无损坏或变形
			Dielectric Strength 耐电压	500V(AC)
七. MECHANICAL(机械性能):				
7-1	INSERTION WITHDRAWAL FORCE 插拔力	1.The test method complies with EIA-364-13 测试方法依照 EIA-364-13 2. The speed at25±3mm/minute 插拔速率为每分钟 25±3mm。	Lock force 压入(锁卡)	1.4kg MAX
			Lock release force 压入(退卡)	1.4kg MAX
7-2	TERMINAL RETENTION FORCE 端子保持力	1.The test method complies with EIA-364-29 测试方法依照 EIA-364-29 2.Push out@25 ± 3mm/minute 插拔力速率为每分钟 25±3mm	Retention force 保持力	0.1kgf MIN/PIN
7-3	DURABILITY 耐插拔	1. The test method complies with EIA-364-09 测试方法依照 EIA-364-09 2. Durability with 5000 cycles 插拔 5000 次	Appearance 外观	No damage or deformation 无损坏或变形

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		3. The applicable durability unit Specification is: 使用插拔件规格是: TFR CARD & CONNECTOR EACH OTHER 卡与连接器对插 400-600 Cycle/Hour	Contact Resistance 接触阻抗	100mΩ ± 40 mΩ MAX
八. THERMAL(耐热性能):				
8-1	Humidity 恒温恒湿	1.Test method complies with EIA-364-31 测试方法依照 EIA-364-31 2.Subject samples to temperature of 40 ± 2 °C and a relative humidity of 90 ~ 95% for a period of 96 hours 本产品温度在 40 ± 2 °C, 相对湿度为 90% ~ 95%RH 经 96 小时试验后经常温干燥	Appearance 外观	No Damage or deformation 无损坏或变形
			Contact Resistance 接触阻抗	100mΩ ± 40 mΩ MAX
			Insulation Resistance 绝缘阻抗	100MΩ MIN
			Dielectric Strength 耐电压	500V(AC)
8-2	Heat Resistance 耐热性	1.The test method complies with EIA-364-17 测试方法依照 EIA-364-17 2.Subject samples to temperature of +85°C ± 2°C of accuracy oven of 96 hours 本产品温度在 +85°C ± 2°C 环境中放置 96 小时	Appearance 外观	No Damage or deformation 无损坏或变形
			Contact Resistance 接触阻抗	100mΩ ± 40 mΩ MAX
8-3	Cold Resistance 耐低温	1.Test method complies with EIA-364-59 测试方法依照 EIA-364-59 2.It shall be subjected to temperature of -40 ± 3 °C for 96 hours 本产品温度在 -40 ± 3 °C 环境中试验 96 小时	Appearance 外观	No Damage or deformation 无损坏或变形
			Contact Resistance 接触阻抗	100mΩ ± 40 mΩ MAX
8-4	Thermal Shock 热冲击	1.Test method complies with EIA-364-32 测试方法依照 EIA-364-32 2.It shall be subjected to temperature of -55 ± 3 °C for 30 minutes, +85 °C ± 2 °C for 30 minutes, Time of cycles:5 cycles. 本产品在高温、低温中循环 5 次, 测试条件为 -55 ± 3 °C 30 分钟、+85 °C ± 2 °C 30 分钟	Appearance 外观	No Damage or deformation 无损坏或变形
			Contact Resistance 接触阻抗	100mΩ ± 40 mΩ MAX

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8-5	Resistance to Soldering Heat 耐焊锡热性	<p>1.Test method complies with EIA-364-56 测试方法依照 EIA-364-56</p> <p>2.1.Connector mounted on PCB,Solder tail shall be immersed in soldering bath at temperature of 250 for 10.0±0.5 sec (be Applied SMT Type).产品贴于 PCB 板, PCB 板与连接器同处于温度 250°C MAX 中, 时间 10.0±0.5 Sec (适用于 SMT 型)</p> <p>2.2.Connector mounted on PCB,Solder tail shall be immersed in soldering bath at temperature of 350±5°C for 3±1 sec (be Applied DIP Type).本产品穿过 PCBS 板, 焊接尾部浸在温度 350±5°C 锡炉中浸锡 3±1 sec(适用于 DIP 型)</p>	Appearance 外观	No Damage or deformation 无损坏或变形
九. OTHERS (其他):				
9-1	Solder-ability 沾锡性	<p>1. Test method complies with EIA-364-52 测试方法依照 EIA-364-52</p> <p>2.The connector shall be immersed into solder of 230±5°C for 3.0±0.5 sec. 本产品端子浸在温度 230±5°C 锡炉中, 沾锡 3±0.5 sec.</p>	Solder Wetting 端尾焊锡	A new uniform coating of solder shall cover 95% of the surface being immersed 焊锡面积 95%以上
9-2	Vibration 振动试验	<p>1.Test method complies with EIA-364-28 测试方法依照 EIA-364-28</p> <p>2.Measure change in contact resistance after 2 hours of vibration in reach of the X.Y and Z directions. Frequency varying in 1 Minutes sweeping as 10~55 ~ 10 Hz with 1.5mm amplitude. 本产品在频率 10~55 ~ 10Hz/ 分钟, 振动幅度 1.5mm, X.Y.Z 轴各振动 2 小时.</p>	Appearance 外观	No Damage or deformation 无损坏或变形
			Contact Resistance 接触阻抗	100mΩ±40 m Ω MAX
			Discontinuity 瞬断	1us max

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9-3	Salt Sprat 盐水试验	1.Test method complies with EIA-364-26 测试方法依照 EIA-364-26 2.Subject test samples to a salt water spray having a concentration of $5 \pm 1\%$ for 48 hours at a temperature of 35%, Measure resistance before and after salt spray exposure. 本产品 在 35℃.盐水浓度 $5 \pm 1\%$ 经 48 小时喷雾后,经常温水洗,常温干燥.	Appearance 外观	No Damage or deformation 无损坏或变形
			Contact Resistance 接触阻抗	$100m\Omega \pm 40 m\Omega$ MAX
9-4	Mixed Flowing Gas 混合流动气体试验	1.Test method complies with EIA-364-65 测试方法依照 EIA-364-65 2.Environmental Class II for 96 houre with connector unmated 在连接器未配合状态下依环境等级 II 标准测试 96 小时	Appearance 外观	No Damage or deformation 无损坏或变形
			Contact Resistance 接触阻抗	$100m\Omega \pm 40 m\Omega$ MAX
9-5	Mechanical Shock 机械冲击	1.The test method complies with EIA-364-27 测试方法依照 EIA-364-27 2.The faired maximum value of the measured pulse shall be within $\pm 20\%$ of of the specified ideal pulse amplitude, its duration shall be within $\pm 15\%$ of the specified ideal pulse duration, and the velocity change associated with the measure pulse shall be within $\pm 10\%$ of $V_i=2AD/\pi$ 测试波合理的最大值应在设定理想值 $\pm 20\%$ 的范围内,持续时间应在设定理想值 $\pm 15\%$ 范围内,与被测波形相联系的速度改变应在 $V_i=2AD/\pi$ 范围内。	Appearance 外观	No Damage or deformation 无损坏或变形
			Contact Resistance 接触阻抗	$100m\Omega \pm 40 m\Omega$ MAX
			Discontinuity 瞬断	1μsec max

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十.CONNECTOR USING（连接的应用）

10.1.Fitting for P.C.B layout specification

适配的 P.C.B 布局规格(见产品图面之 LAYOUT 规格)

10.2.The standard TFR memory card

标准的 TFR 记忆卡

*** 标准 TFR MEMORY CARD ***（依相应 CARD 协会标准）

十一.CONNECTOR OPERATION METHOD AND NOTICES(连接器的使用方法与注意事项)

11-1.Memory card inserting connector method

记忆卡插入连接器的方法

1. Memory card starts use after pushing into the fixed position

插入并推动记忆卡至定位后，开始连接读卡

11-2. Memory card withdrawing from connector method

记忆卡从连接器退出的方法

1. Press into the memory card again,the card ejecting from the connector,the usage is stop

再次压入记忆卡，记忆卡从连接器弹出，停止读卡。

11-3 Notices

注意事项

****注意插入的正确方向及位置。****

Please use caution when ejecting the card from the connector.

当记忆卡从连接器弹出时，请小心使用。

When pushing the card in to remove it from the connector slot,the spring force could cause the card to pop out and project from the connector if finger is to slip or card is removed improperly.

当按动记忆卡使之从连接器卡槽弹出时，弹簧的力量会使记忆卡弹出，然而用手指拨弄记忆卡或不正确的方法拔出记忆卡，也会使记忆卡弹出连接器。

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十二 TEST SEQUENCE(测试顺序)

ITEM 序号	TEST DESCRIPTION 测试内容	TEST SEQUENCE 测试频次								TEST METHODS 测试方
		A	B	C	D	E	F	G		
1	EXAMINATION FOR PRODUCT 外观	1,7	1,3	1,3	1,3	1,3	1, 3, 5	1,4		
2	CONTACT RESISTANCE 接触阻抗	2,8	4	4	4	4				6-1
3	INSULATION RESISTANCE 绝缘阻抗	3	5							6-2
4	DIELECTRIC WITHSTANDING VOLTAGE 耐电压	4	6							6-3
5	INSERTIONWITHDRAWAL FORCE 插拔力	5,9								7-1
6	RETENTION FORCE 保持力	10								7-2
7	DURABILITY 耐插拔	6								7-3
8	HUMIDITY 恒温恒湿		2							8-1
9	HEAT RESISTANCE 耐热性			2						8-2
10	COLD RESISTANCE 耐低温				2					8-3
11	THERMAL SHOCK 热冲击					2				8-4
12	RESISTANCE TO SOLDER HEAT 耐焊锡热性						2			8-5
13	SOLDERABILITY 沾锡性						4			9-1
14	VIBATION 振动试验							2		9-2
15	SALT SPRAY 盐水喷雾									9-3
16	MIXED FLOWING GAS 混合流动气体实验									9-4
17	MECHANICAL SHOCK 机械冲击							3		9-5
	SAMPLE SIZE 样品数量	4	4	4	4	4	4	4		TOTAL 28